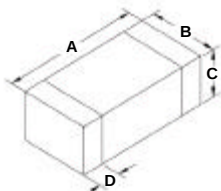
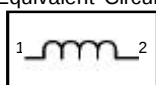
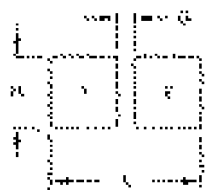
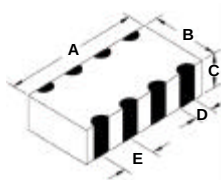
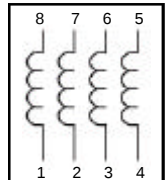
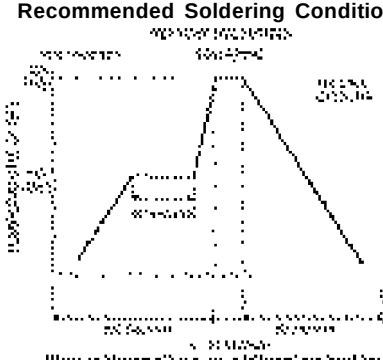
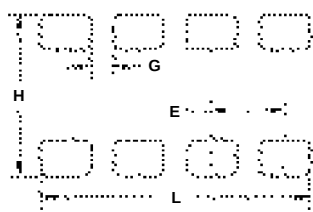


Chip Size						Land Patterns for Reflow Soldering					
 	Metric (EIA) Pkg. Size	A mm (inches)	B mm (inches)	C mm (inches)	D mm (inches)	 Chip Bead	L**	G	H		
	1005 (0402)	1.01 ± 0.18 (0.040 ± 0.007)	0.50 ± 0.20 (0.020 ± 0.008)	0.50 ± 0.20 (0.020 ± 0.008)	0.30 MAX (0.012 MAX)		2.10 (0.083)	0.50 (0.020)	0.55 (0.022)		
	1608 (0603)	1.60 ± 0.15 (0.063 ± 0.006)	0.80 ± 0.15 (0.031 ± 0.006)	0.80 ± 0.15 (0.031 ± 0.006)	0.36 ± 0.15 (0.014 ± 0.006)		2.60 (0.102)	0.60 (0.023)	0.80 (0.031)		
	2012 (0805)	2.00 ± 0.20 (0.079 ± 0.008)	1.25 ± 0.20 (0.049 ± 0.008)	0.90 ± 0.20 (0.035 ± 0.008)	0.51 ± 0.25 (0.020 ± 0.010)		3.00 (0.118)	1.00 (0.039)	1.00 (0.039)		
	2012 (0805)	2.00 ± 0.20 (0.079 ± 0.008)	1.25 ± 0.20 (0.049 ± 0.008)	1.25 ± 0.20 (0.049 ± 0.008)	0.51 ± 0.25 (0.020 ± 0.010)		3.00 (0.118)	1.00 (0.039)	1.00 (0.039)		
	3216 (1206)	3.20 ± 0.20 (0.126 ± 0.008)	1.60 ± 0.20 (0.063 ± 0.008)	1.10 ± 0.20 (0.043 ± 0.008)	0.51 ± 0.25 (0.020 ± 0.010)		4.40 (0.173)	2.20 (0.087)	1.40 (0.055)		
	3225 (1210)	3.20 ± 0.20 (0.126 ± 0.008)	2.50 ± 0.20 (0.098 ± 0.008)	1.40 ± 0.20 (0.055 ± 0.008)	0.46 ± 0.20 (0.018 ± 0.008)		4.06 (0.160)	1.62 (0.084)	2.92 (0.115)		
	4030 (1612)	4.06 ± 0.20 (0.160 ± 0.008)	3.05 ± 0.20 (0.120 ± 0.008)	2.28 ± 0.20 (0.090 ± 0.008)	0.46 ± 0.20 (0.018 ± 0.008)		8.64 (0.340)	2.13 (0.084)	4.06 (0.160)		
	4516 (1806)	4.50 ± 0.25 (0.177 ± 0.010)	1.60 ± 0.25 (0.063 ± 0.010)	1.60 ± 0.25 (0.063 ± 0.010)	0.51 ± 0.25 (0.020 ± 0.010)		5.70 (0.224)	2.70 (0.106)	1.40 (0.055)		
	4532 (1812)	4.50 ± 0.25 (0.177 ± 0.010)	3.20 ± 0.25 (0.126 ± 0.010)	1.40 ± 0.25 (0.055 ± 0.010)	0.46 ± 0.20 (0.018 ± 0.008)		5.90 (0.232)	2.57 (0.101)	4.22 (0.166)		
	5650 (2220)	5.59 ± 0.51 (0.220 ± 0.020)	5.08 ± 0.25 (0.200 ± 0.010)	3.45 ± 0.25 (0.136 ± 0.010)	0.76 ± 0.25 (0.030 ± 0.008)		9.19 (0.362)	3.07 (0.121)	6.10 (0.240)		
	6350 (2520)	6.40 ± 0.51 (0.252 ± 0.020)	5.00 ± 0.25 (0.197 ± 0.010)	3.00 ± 0.25 (0.118 ± 0.010)	0.76 ± 0.25 (0.030 ± 0.010)		9.50 (0.374)	3.81 (0.1507)	6.10 (0.240)		
	8530 (3312)	8.50 ± 0.20 (0.335 ± 0.008)	3.05 ± 0.20 (0.120 ± 0.008)	2.28 ± 0.20 (0.090 ± 0.008)	0.51 ± 0.25 (0.020 ± 0.010)		13.08 (0.515)	6.48 (0.255)	4.06 (0.160)		
4-Line Chip Array Size						Land Patterns for Reflow Soldering					
 	Metric (EIA) Pkg. Size	A mm (inches)	B mm (inches)	C mm (inches)	D mm (inches)	 Wave soldering with required preheating and dwell time	 4-Line Array	L**	G	H	E
	3216 (1206)	3.20 ± 0.20 (0.126 ± 0.008)	1.60 ± 0.20 (0.063 ± 0.008)	1.10 ± 0.20 (0.043 ± 0.008)	0.40 ± 0.15 (0.016 ± 0.006)						
** - For wave soldering, add 0.762mm (0.030") to the L dimension											

** - For wave soldering, add
0.762mm (0.030") to the L dimension

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